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ABSTRACT

2 A method of forming a socket device for receiving a connection pin is disclosed, the
3 socket device including a substrate having an upper surface. The socket device includes a
4 connection pad disposed on the upper surface and a first layer disposed on the upper surface and
5 on the connection pad. The first layer includes material having an overall positive coefficient of
6 thermal expansion, and may be formed on the upper surface using conventional spin-on
7 deposition techniques. The socket device includes a second layer disposed on the first layer. The
8 second layer includes material having an overall negative coefficient of thermal expansion. The
9 socket device also includes a contact aperture formed in the first and second layers using
10 conventional techniques such as photolithography or laser drilling. The contact aperture exposes
11 a portion of the connection pad such that a connection pin inserted into the aperture can contact
12 the connection pad.